

NZ9F2V4T5G, SZNZ9F2V4T5G SERIES

Zener Voltage Regulators

250 mW SOD-923 Surface Mount

This series of Zener diodes is packaged in a SOD-923 surface mount package. They are designed to provide voltage regulation protection and are especially attractive in situations where space is at a premium. They are well suited for applications such as cellular phones, hand held portables, and high density PC boards.

Specification Features:

- Standard Zener Breakdown Voltage Range – 2.4 V to 24 V
- Steady State Power Rating of 250 mW
- Small Body Outline Dimensions:
0.039" x 0.024" (1.00 mm x 0.60 mm)
- Low Body Height: 0.016" (0.40 mm)
- ESD Rating of Class 3 (>16 kV) per Human Body Model
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Mechanical Characteristics:

CASE: Void-free, transfer-molded, thermosetting plastic
Epoxy Meets UL 94 V-0

LEAD FINISH: 100% Matte Sn (Tin)

MOUNTING POSITION: Any

QUALIFIED MAX REFLOW TEMPERATURE: 260°C

Device Meets MSL 1 Requirements

MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, (Note 1) @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	250 2.0	mW mW/°C
Thermal Resistance from Junction-to-Ambient	$R_{\theta JA}$	500	°C/W
Junction and Storage Temperature Range	T_J, T_{stg}	-65 to +150	°C

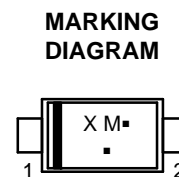
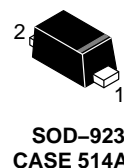
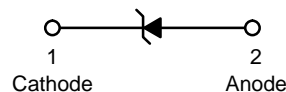
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. FR-4 Minimum Pad.



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X = Specific Device Code
M = Month Code
▪ = Pb-Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
NZ9FxxxxT5G, SZNZ9FxxxxT5G	SOD-923 (Pb-Free)	8000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

DEVICE MARKING INFORMATION

See specific marking information in the device marking column of the Electrical Characteristics tables starting on page 3 of this data sheet.

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ELECTRICAL CHARACTERISTICS

($T_A = 25^\circ\text{C}$ unless otherwise noted,
 $V_F = 0.9\text{ V Max. @ } I_F = 10\text{ mA}$ for all types)

Symbol	Parameter
V_Z	Reverse Zener Voltage @ I_{ZT}
I_{ZT}	Reverse Current
Z_{ZT}	Maximum Zener Impedance @ I_{ZT}
I_{ZK}	Reverse Current
Z_{ZK}	Maximum Zener Impedance @ I_{ZK}
I_R	Reverse Leakage Current @ V_R
V_R	Reverse Voltage
I_F	Forward Current
V_F	Forward Voltage @ I_F
Θ_{VZ}	Maximum Temperature Coefficient of V_Z
C	Max. Capacitance @ $V_R = 0$ and $f = 1\text{ MHz}$

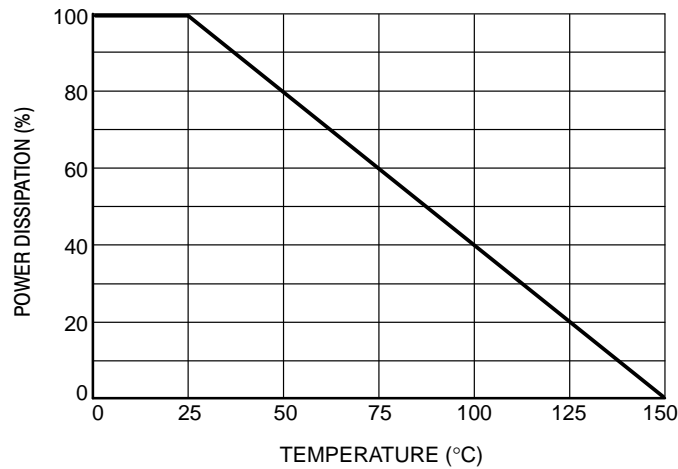
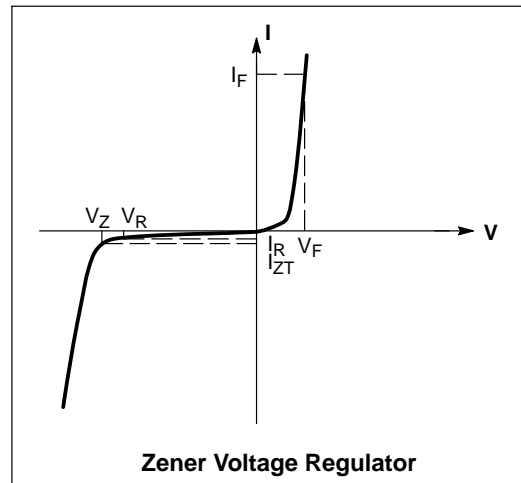


Figure 1. Steady State Power Derating

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ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted, $V_F = 0.9\text{ V Max.}$ @ $I_F = 10\text{ mA}$ for all types)

Device***	Device Marking	Zener Voltage (Note 1)		Zener Impedance			Leakage Current		θ_{V_Z} (mV/k) @ I_{ZT}		C @ $V_R = 0$ $f = 1\text{ MHz}$	
		V_Z (Volts)		$@ I_{ZT}$	Z_{ZT} $@ I_{ZT}$	Z_{ZK} @ I_{ZK}		I_R @ V_R				
		Min	Max	mA	Ω	Ω	mA	μA	Volts	Min	Max	pF
SZ, NZ9F2V4T5G	J	2.28	2.52	5	100	1000	1	50	1	-3.5	0	210
SZ, NZ9F2V7T5G	E**	2.57	2.84	5	100	1000	1	20	1	-3.5	0	210
SZ, NZ9F3V0T5G	T**	2.85	3.15	5	100	1000	1	10	1	-3.5	0	210
SZ, NZ9F3V3T5G	Q	3.14	3.47	5	100	1000	1	10	1	-3.5	0	210
SZ, NZ9F3V6T5G	3**	3.42	3.78	5	100	1000	1	10	1	-3.5	0	210
SZ, NZ9F3V9T5G	V**	3.71	4.10	5	100	1000	1	5	1	-3.5	-2.5	210
SZ, NZ9F4V3T5G	Y**	4.09	4.52	5	100	1000	1	5	1	-3.5	0	210
SZ, NZ9F4V7T5G	3	4.47	4.94	5	100	800	0.5	2	1	-3.5	0.2	150
SZ, NZ9F5V1T5G	4	4.85	5.36	5	80	500	0.5	2	1.5	-2.7	1.2	130
SZ, NZ9F5V6T5G	5	5.32	5.88	5	60	200	0.5	1	2.5	-2.0	2.5	115
SZ, NZ9F6V2T5G	6	5.89	6.51	5	60	100	0.5	1	3	0.4	3.7	110
SZ, NZ9F6V8T5G	A*	6.46	7.14	5	40	60	0.5	0.5	3.5	1.2	4.5	105
SZ, NZ9F7V5T5G	D*	7.13	7.88	5	30	60	0.5	0.5	4	2.5	5.3	100
SZ, NZ9F8V2T5G	E*	7.79	8.61	5	30	60	0.5	0.5	5	3.2	6.2	90
SZ, NZ9F9V1T5G	F*	8.65	9.56	5	30	60	0.5	0.5	6	3.8	7	80
SZ, NZ9F10VT5G	J*	9.50	10.50	5	30	60	0.5	0.1	7	4.5	8	80
SZ, NZ9F11VT5G	K*	10.45	11.55	5	30	60	0.5	0.1	8	5.4	9	80
SZ, NZ9F12VT5G	L*	11.40	12.60	5	30	80	0.5	0.1	9	6	10	80
SZ, NZ9F13VT5G	P*	12.35	13.65	5	37	80	0.5	0.1	10	7	11	75
SZ, NZ9F15VT5G	Q*	14.25	15.75	5	42	80	0.5	0.1	11	9.2	13	70
SZ, NZ9F16VT5G	R*	15.20	16.80	5	50	80	0.5	0.1	12	10.4	14	65
SZ, NZ9F18VT5G	T*	17.10	18.90	5	50	80	0.5	0.1	14	12.4	16	60
SZ, NZ9F20VT5G	V*	19.00	21.00	5	55	100	0.5	0.1	15.4	14.4	18	55
SZ, NZ9F22VT5G	Y*	20.90	23.10	5	55	100	0.5	0.1	16.8	15.4	20	55
SZ, NZ9F24VT5G	F	22.80	25.20	5	70	120	0.5	0.1	18.9	16.8	22	50

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

*Rotated 90°.

**Rotated 270°.

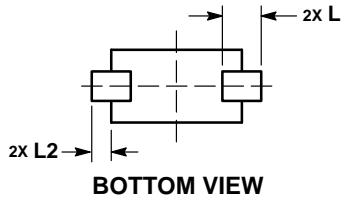
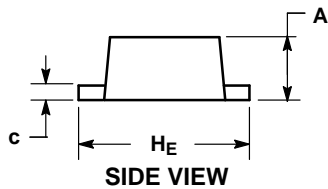
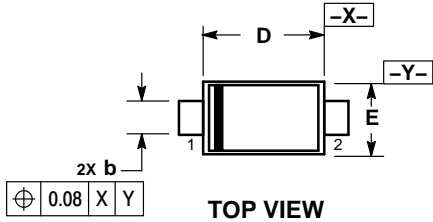
***SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

1. Zener voltage is measured with a pulse test current I_Z at an ambient temperature of 25°C.

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PACKAGE DIMENSIONS

SOD-923
CASE 514AB
ISSUE C

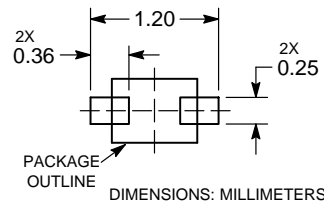


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.34	0.37	0.40	0.013	0.015	0.016
b	0.15	0.20	0.25	0.006	0.008	0.010
c	0.07	0.12	0.17	0.003	0.005	0.007
D	0.75	0.80	0.85	0.030	0.031	0.033
E	0.55	0.60	0.65	0.022	0.024	0.026
H _E	0.95	1.00	1.05	0.037	0.039	0.041
L	0.19 REF			0.007 REF		
L2	0.05	0.10	0.15	0.002	0.004	0.006

SOLDERING FOOTPRINT*



See Application Note AND8455/D for more mounting details

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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